

ABSTRACT

A semiconductor structure includes a semiconductor substrate and a compliant interconnect element disposed on a first surface of the substrate. The compliant interconnect element defines a chamber between the first surface of the substrate and a surface of the compliant interconnect element. The compliant interconnect element can be a compliant layer. The compliant layer can be formed of a polymer, such as silicone. A conductive layer can be disposed on the compliant layer, in contact with a contact pad on the semiconductor substrate. A method for forming a semiconductor structure includes providing a semiconductor substrate and providing a compliant interconnect element on a first surface of the substrate, so that the compliant interconnect element defines a chamber between the compliant interconnect element and the first surface of the substrate.

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